

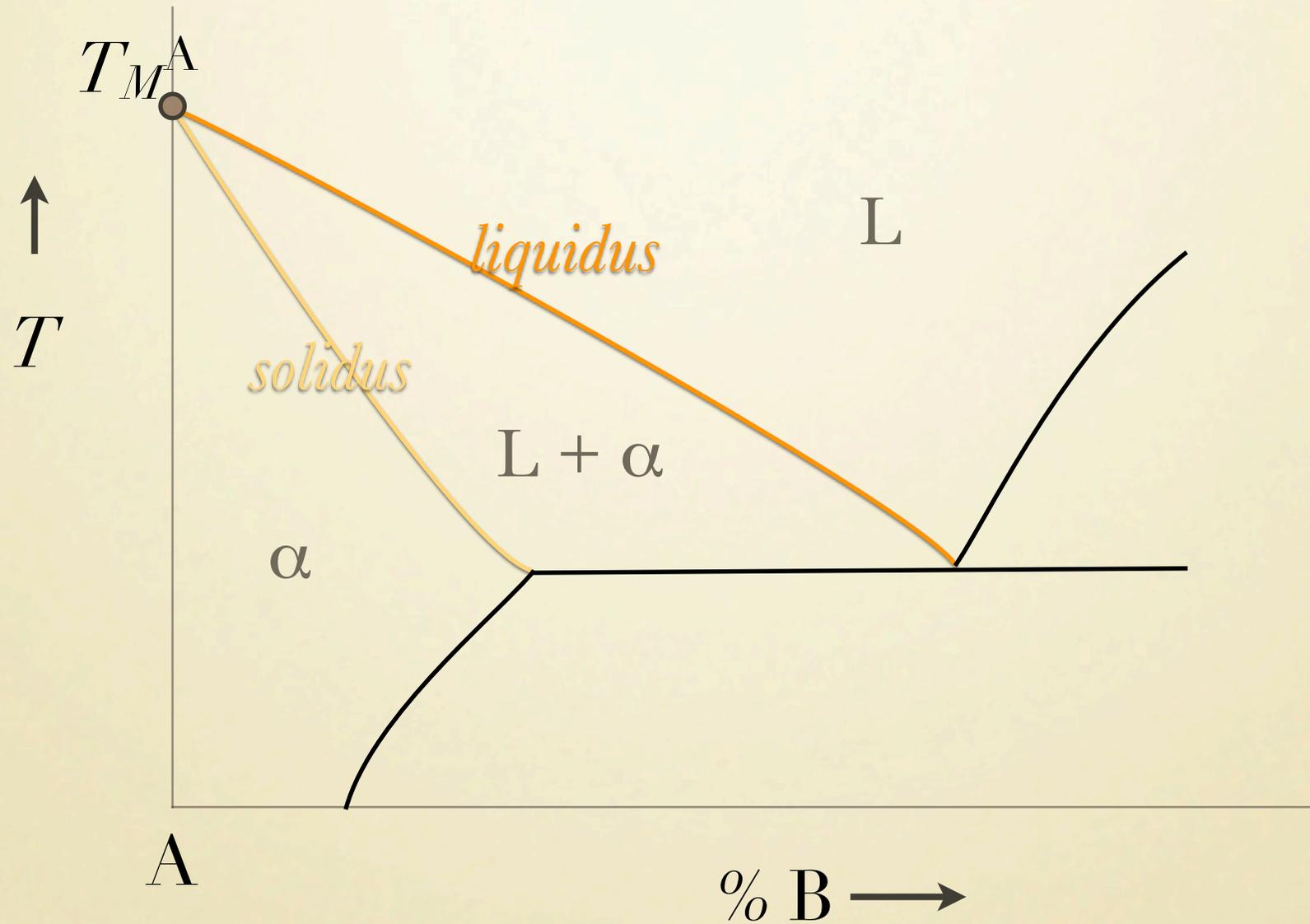
**NANOMATERIALS
SYNTHESIS AND
PROCESSING**

SOLIDIFICATION PROCESSING

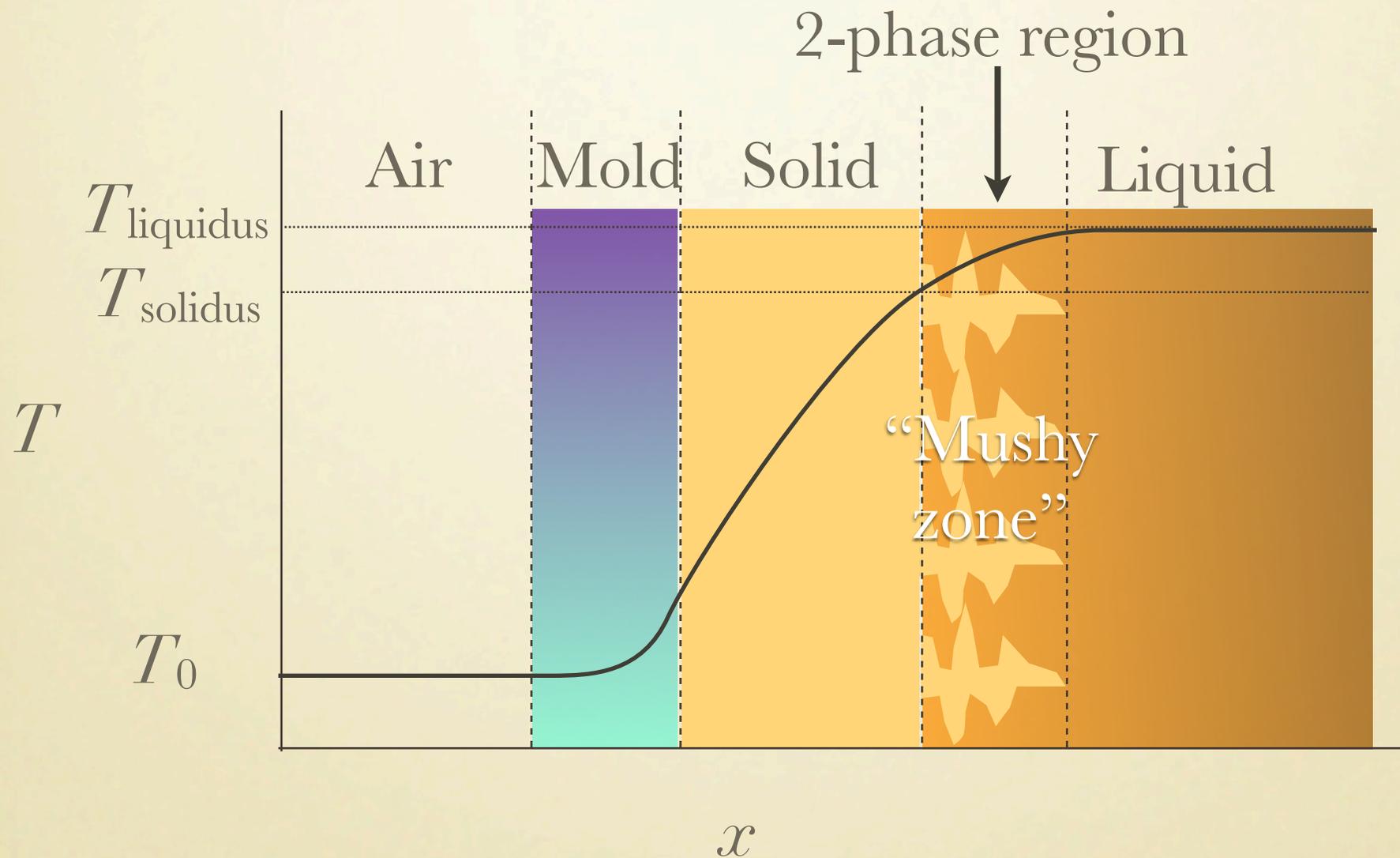
“MELTING POINT”

- Elements melt/solidify at a single temperature (T_M)
- Alloys melt/solidify over a range of temperatures

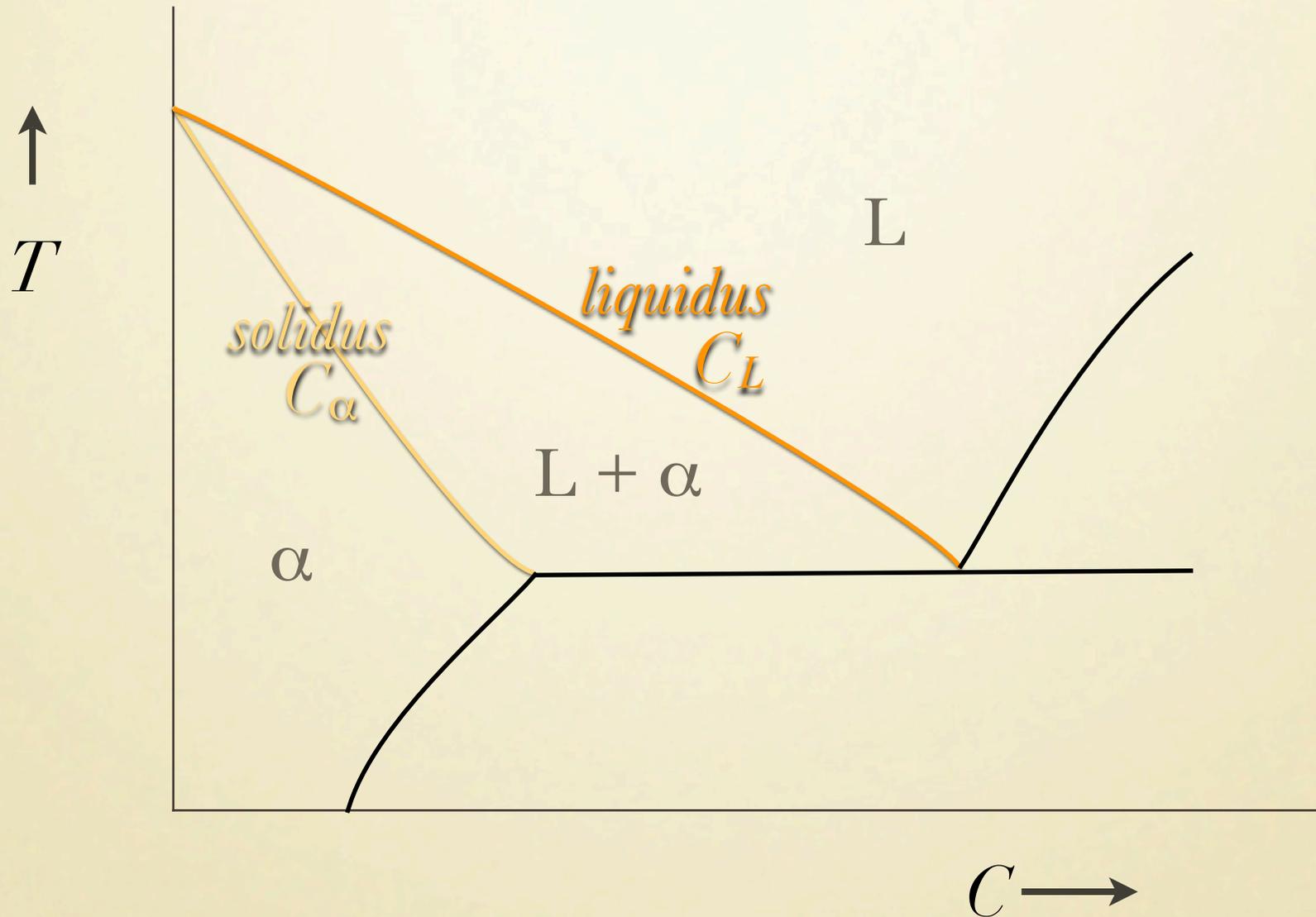
“TWO-PHASE” FIELD

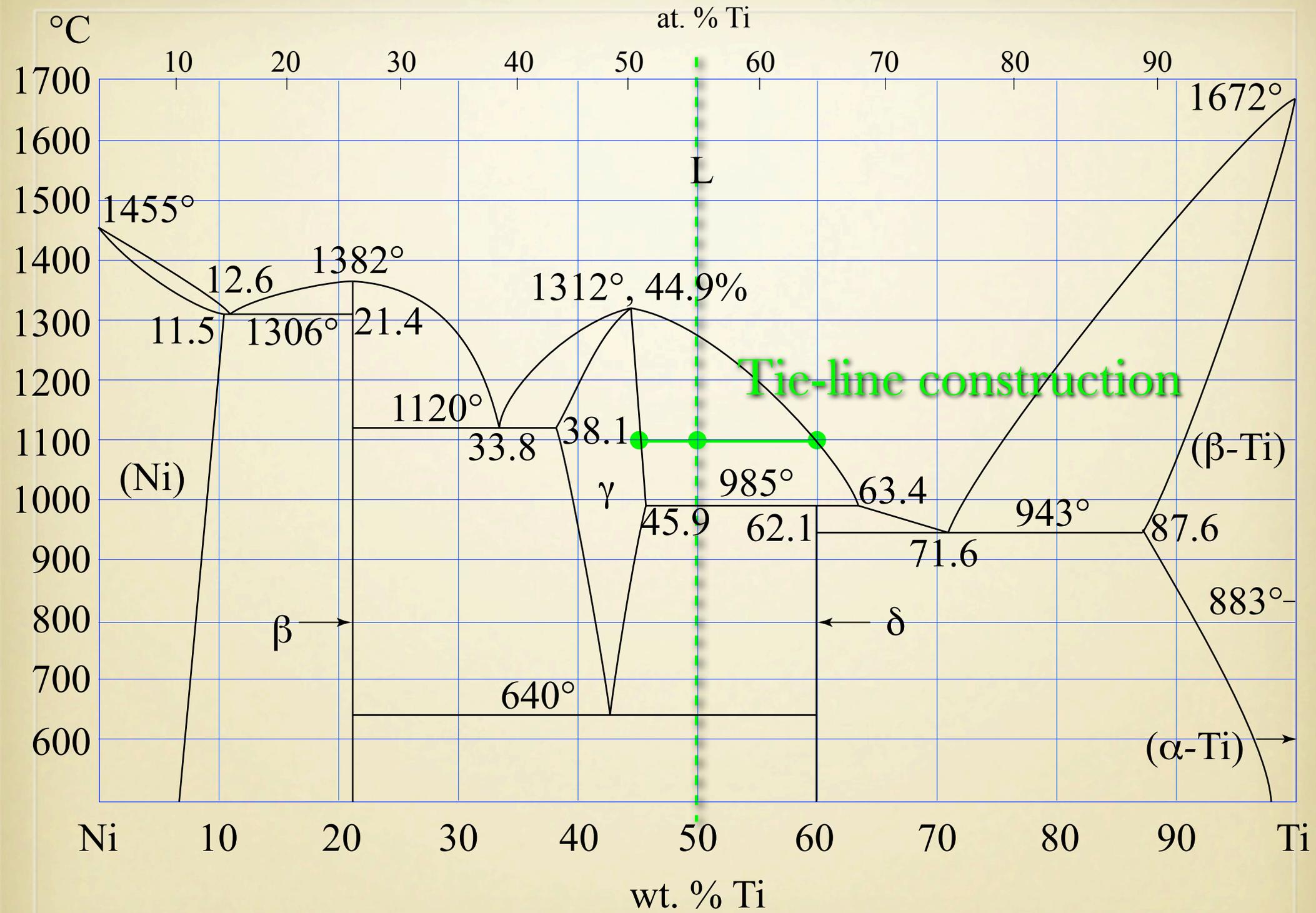


ALLOY SOLIDIFICATION

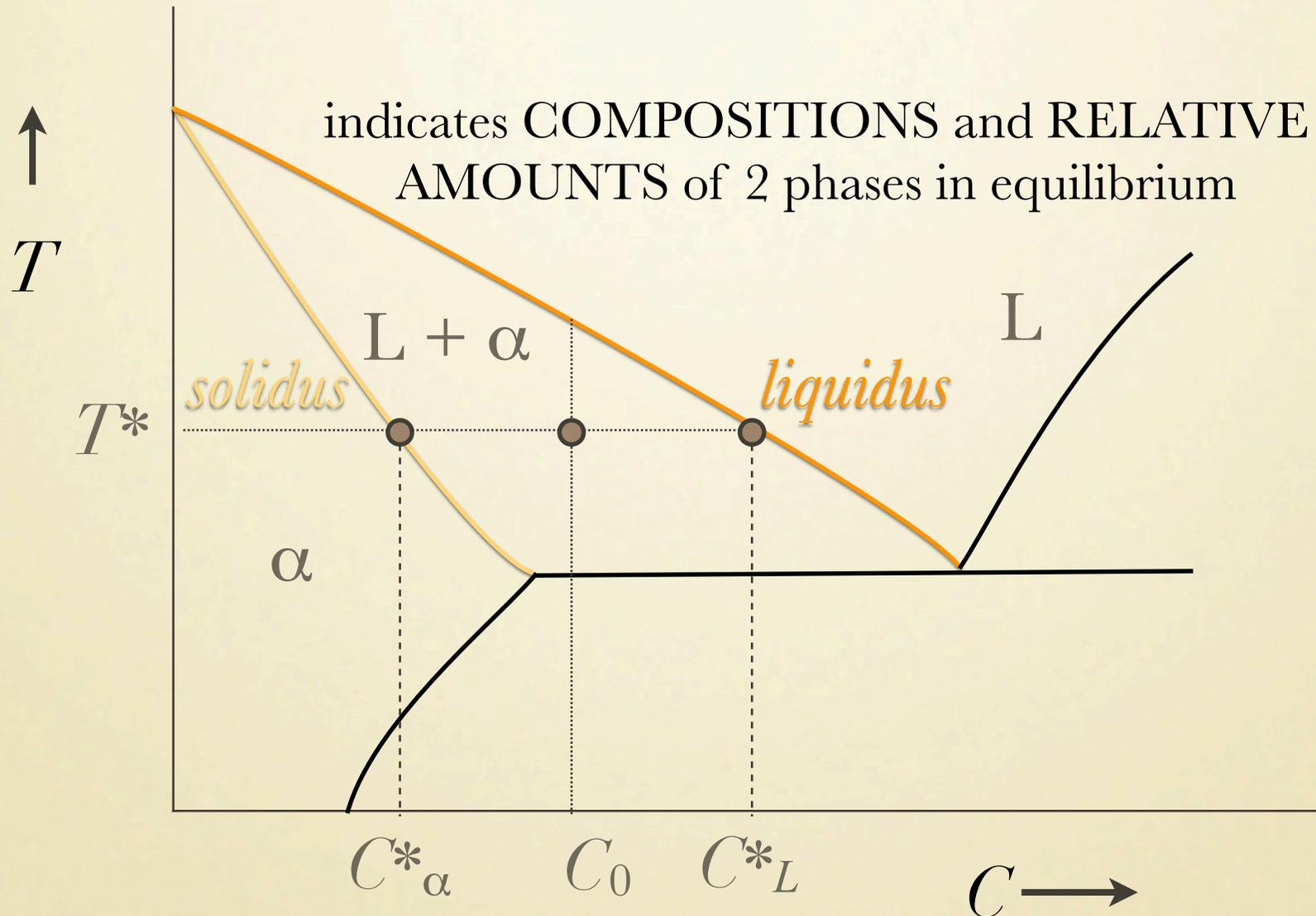


SOLUTE PARTITIONING

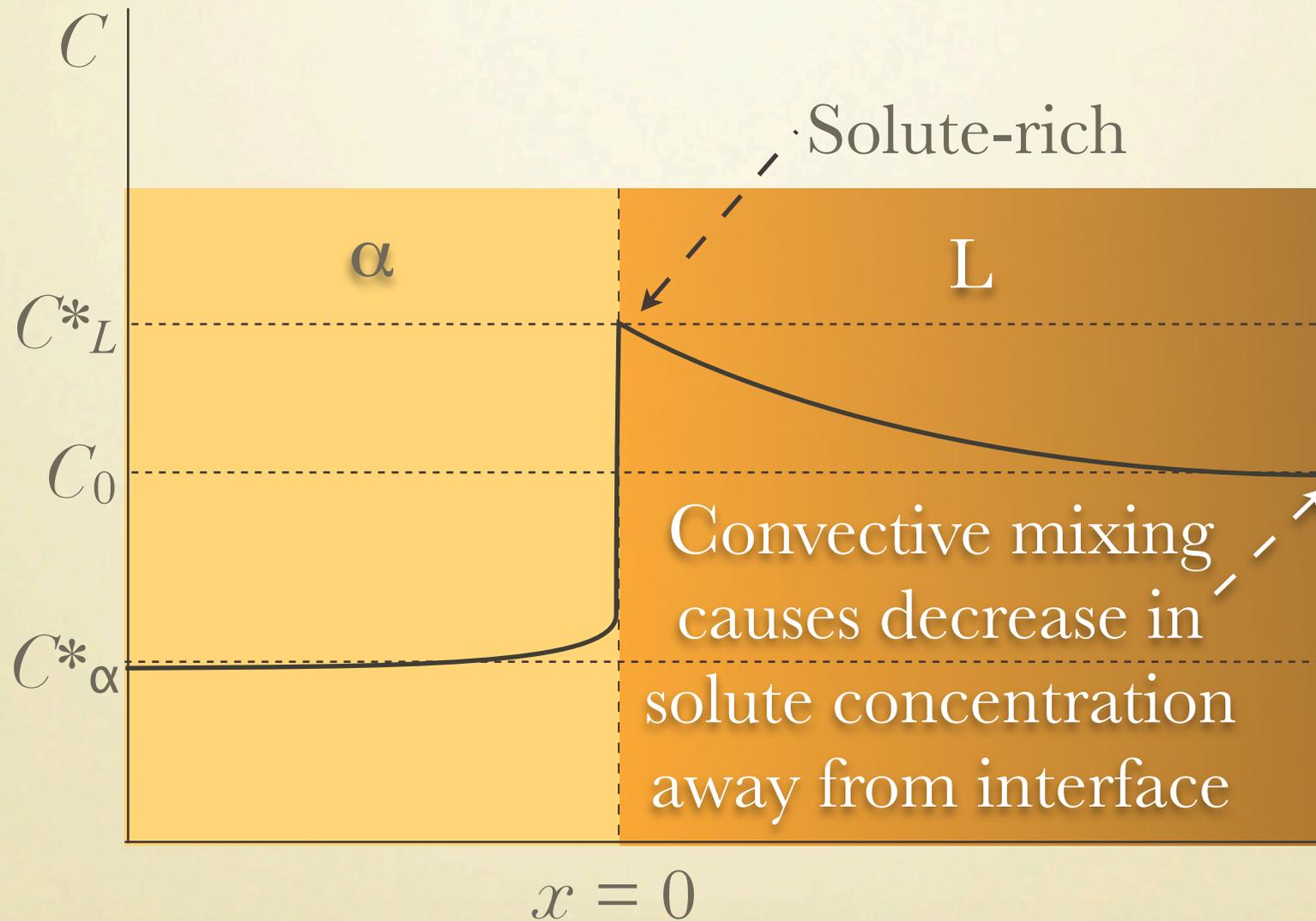




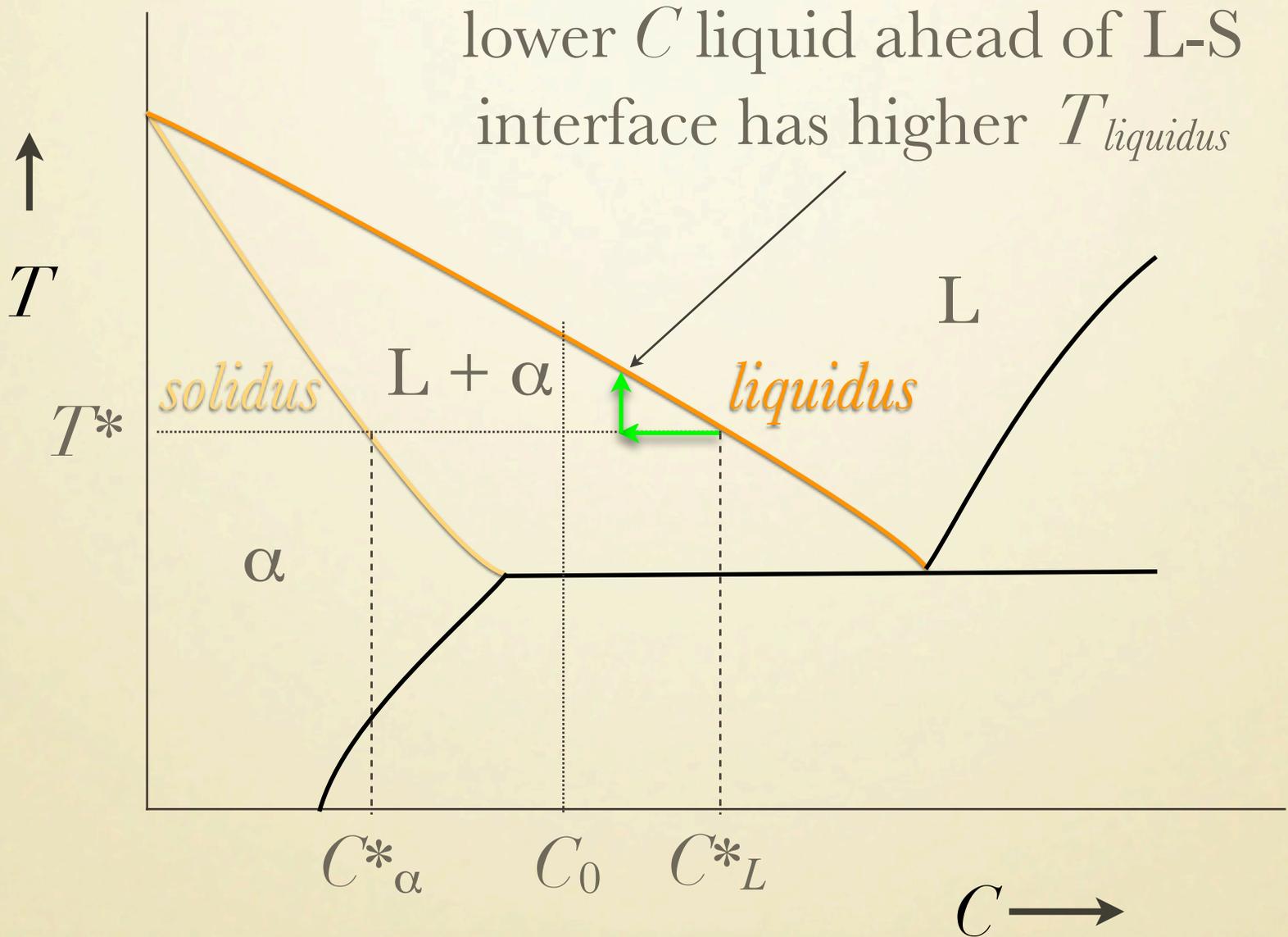
TIE-LINE CONSTRUCTION



BOUNDARY LAYER

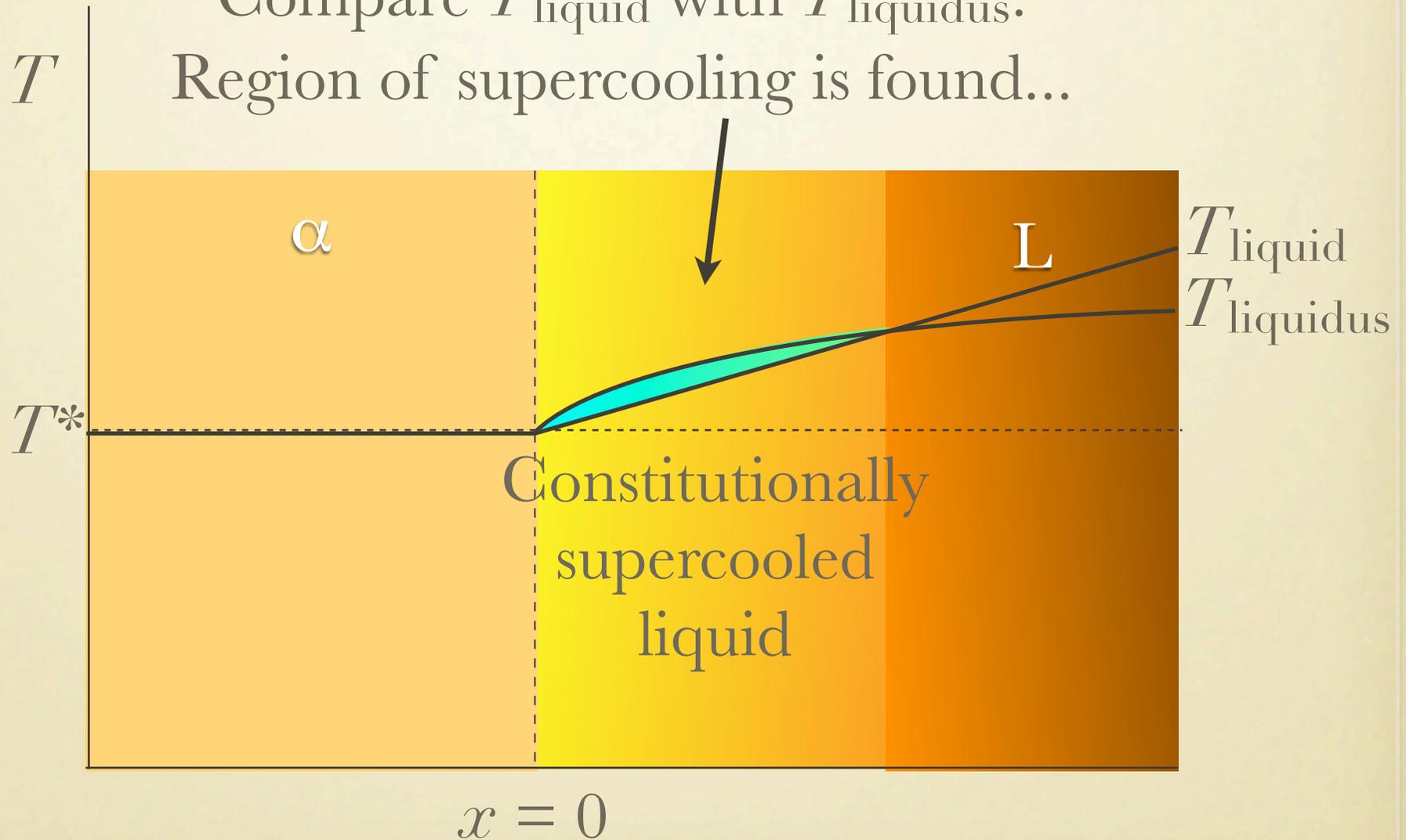


EFFECTIVE LIQUIDUS



SUPERCOOLING

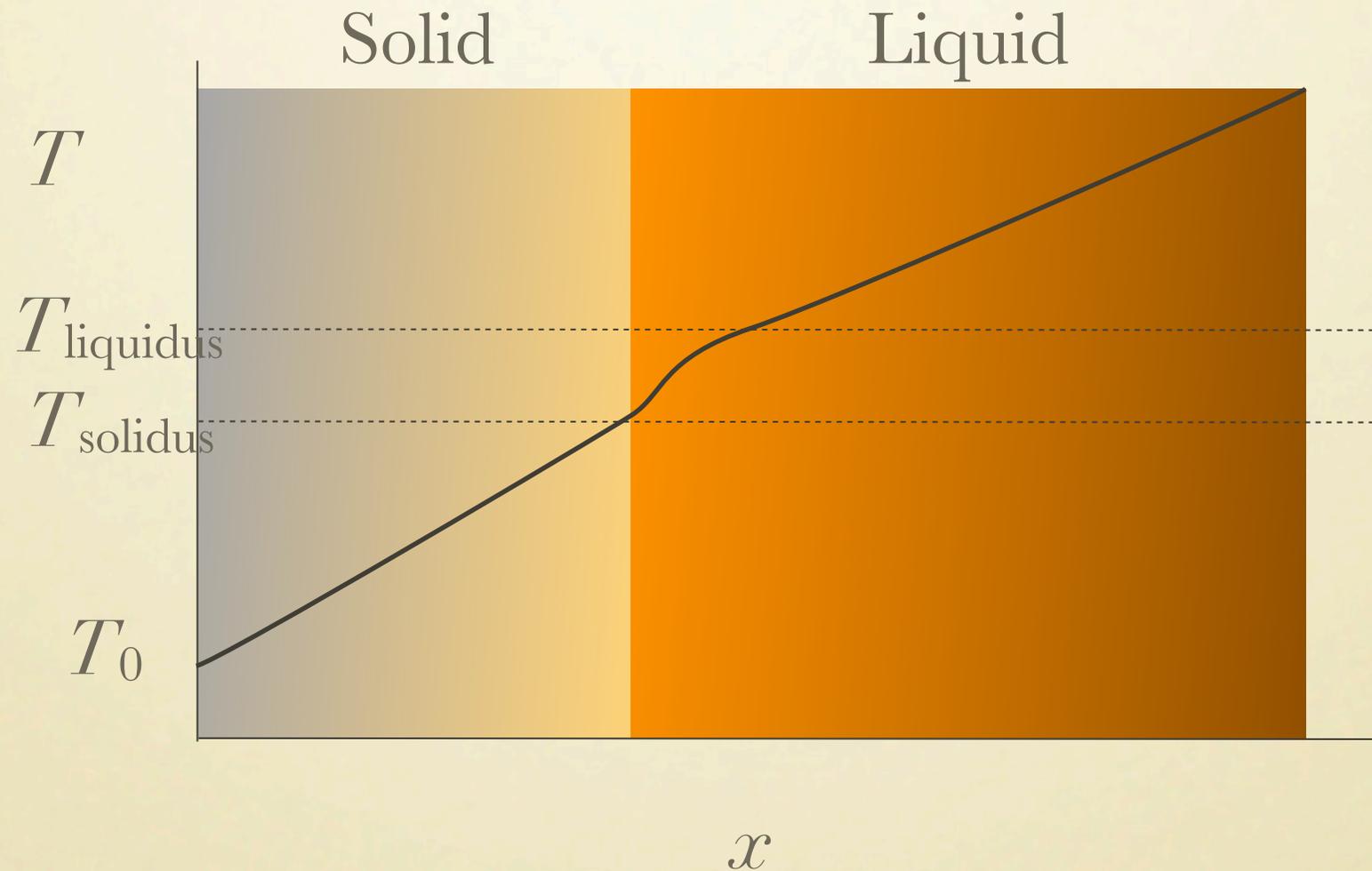
Compare T_{liquid} with T_{liquidus} .
Region of supercooling is found...



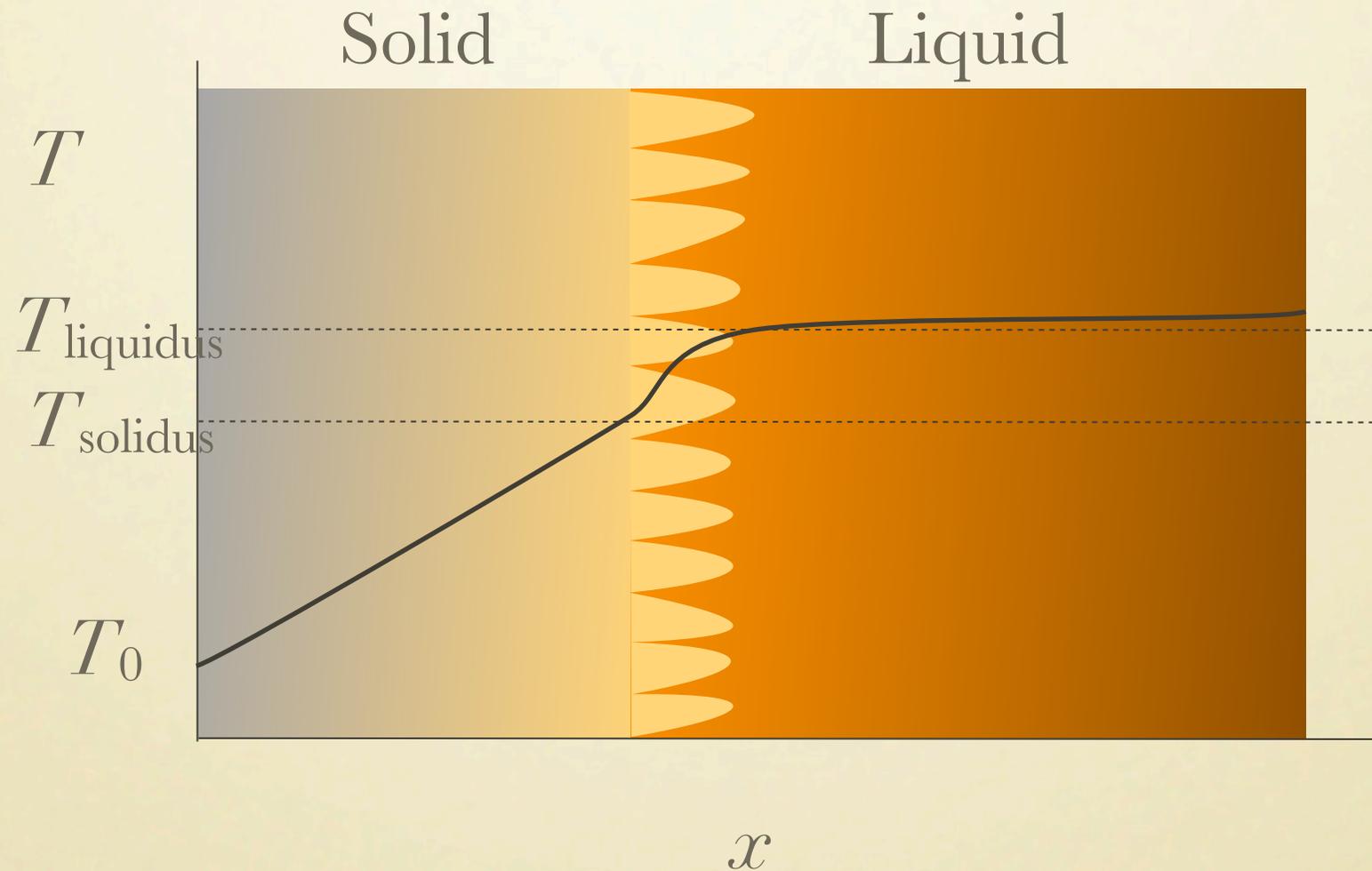
INTERFACE MORPHOLOGY

- At slow growth rates, L-S interface can be “planar.”
- As growth rate increases, L-S interface becomes “cellular.”
- At high growth rate, L-S interface is “dendritic.”
- Dendritic growth directions are preferred crystallographic directions

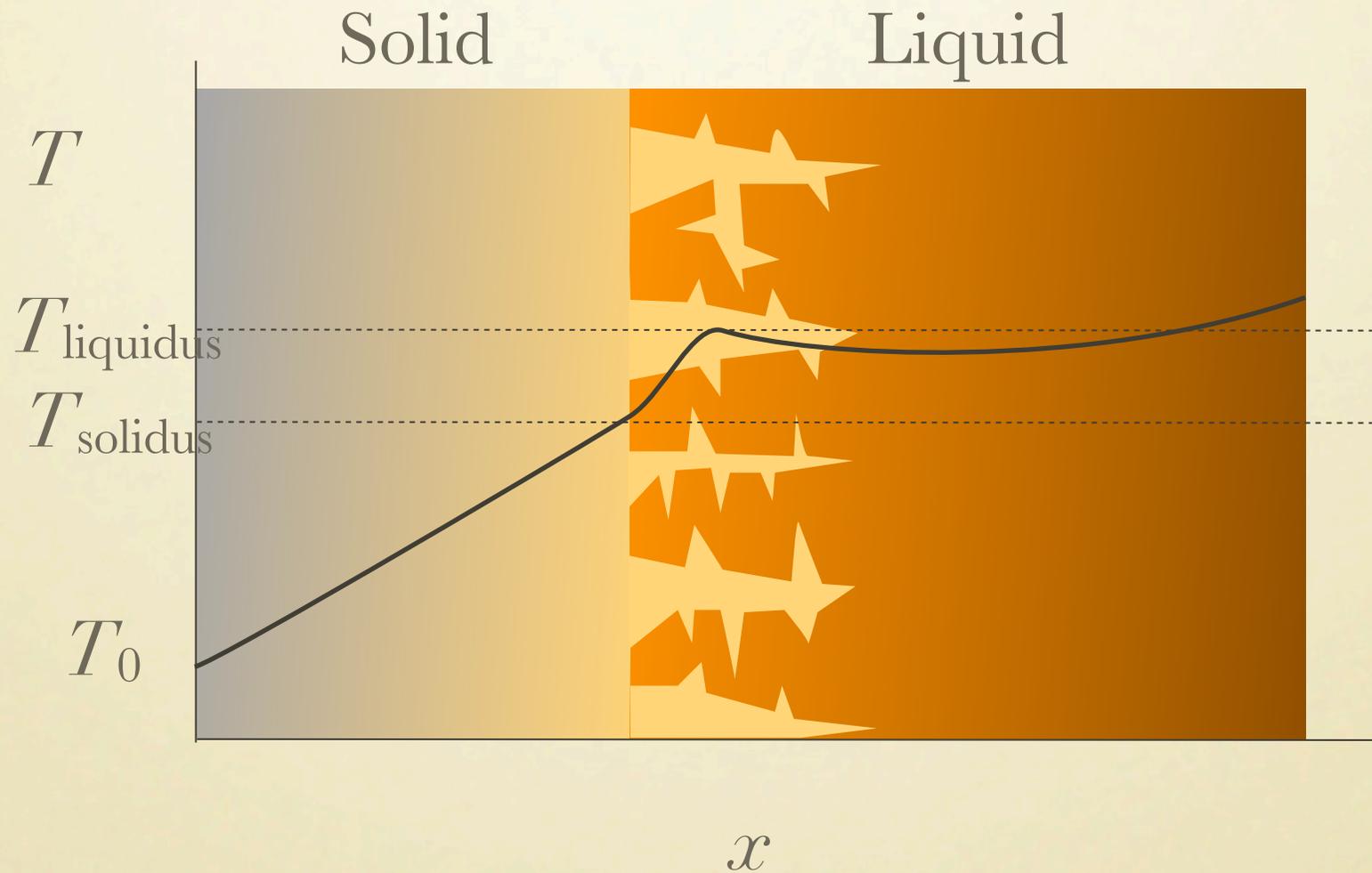
PLANAR GROWTH



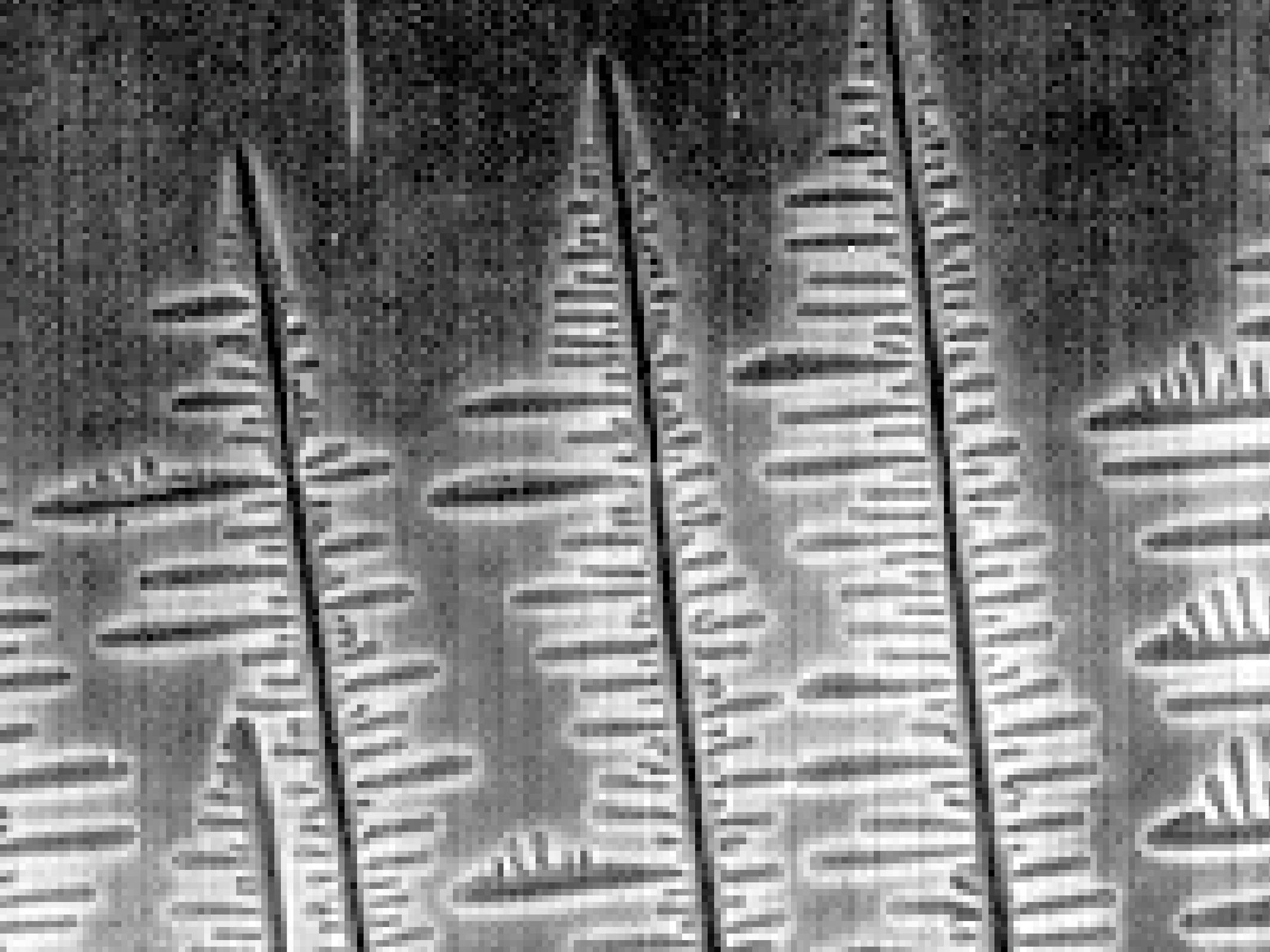
CELLULAR GROWTH

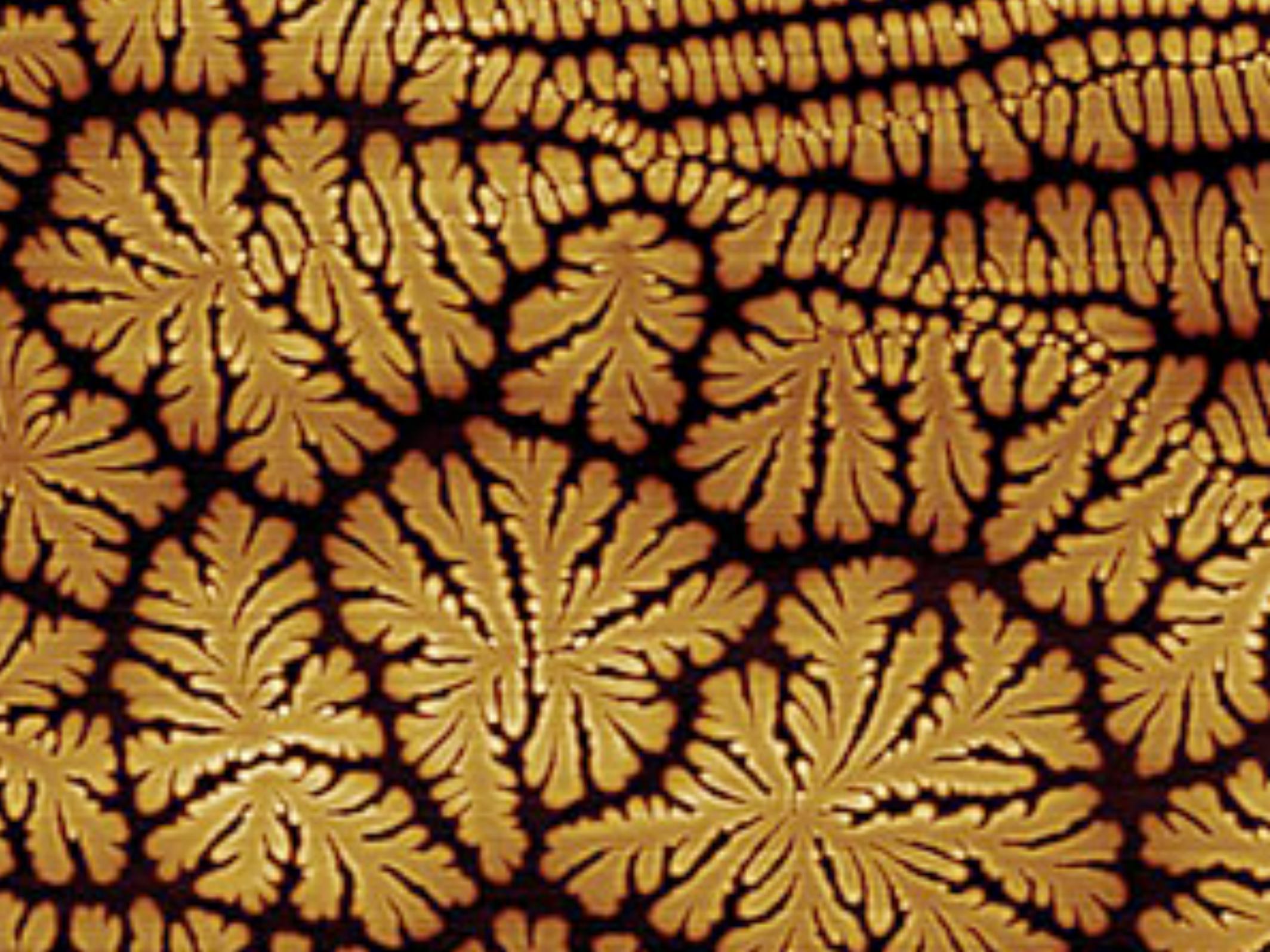


DENDRITIC GROWTH





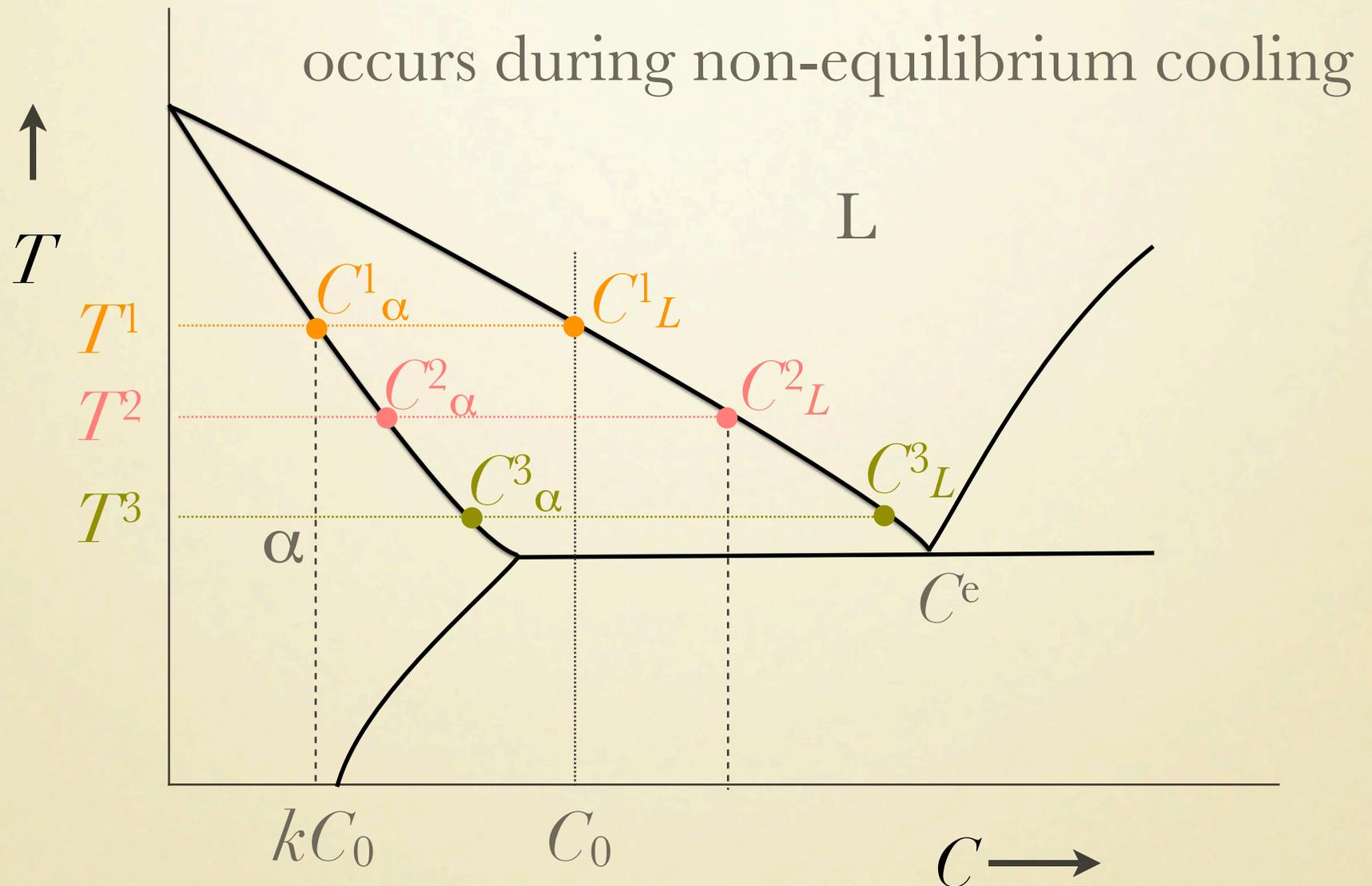




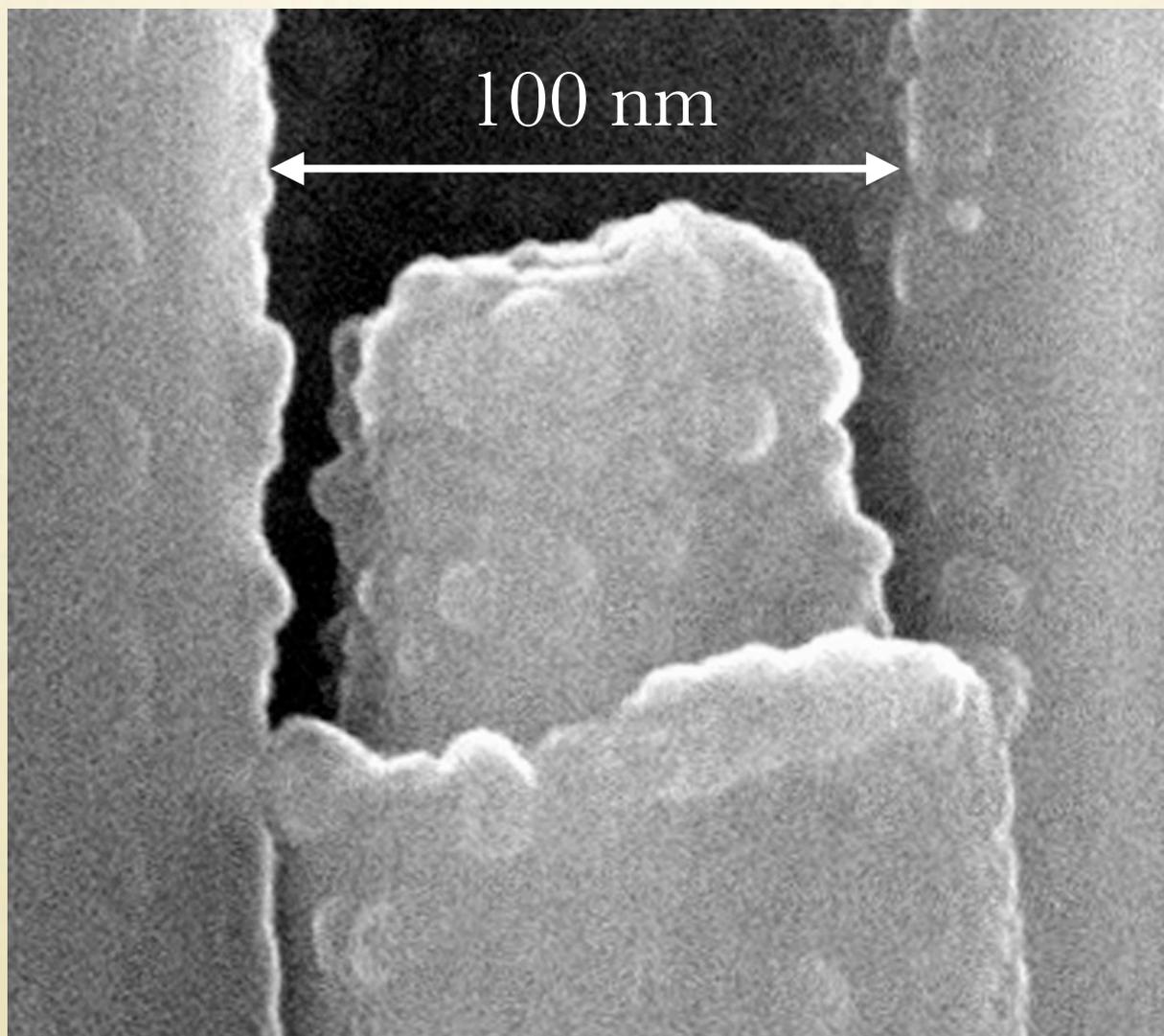




SOLUTE PARTITIONING



CORE & SHELL

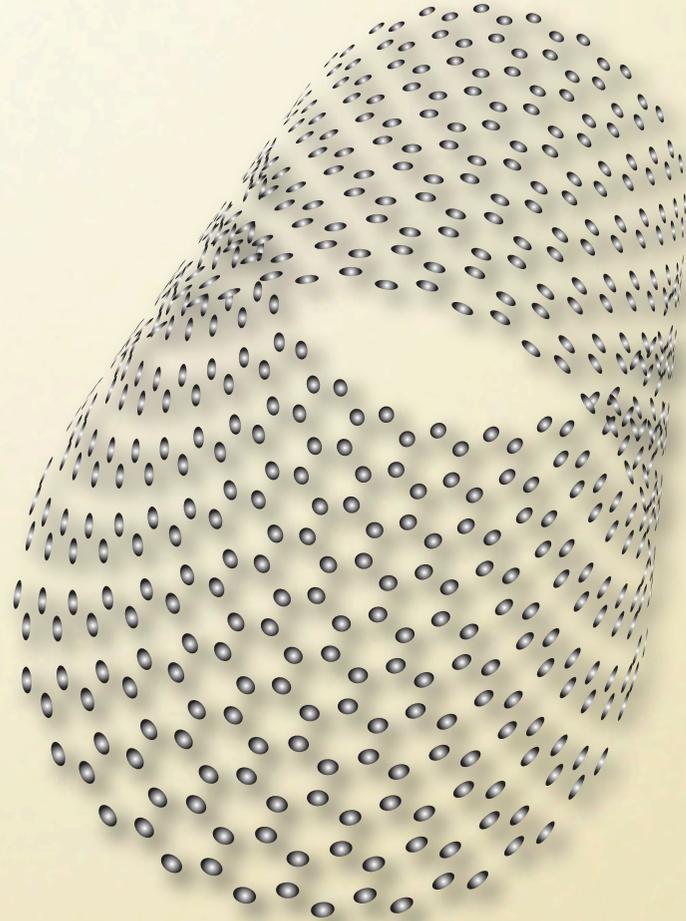


CoSb₃

NANO SYNTHESIS

NANOTUBE SYNTHESIS

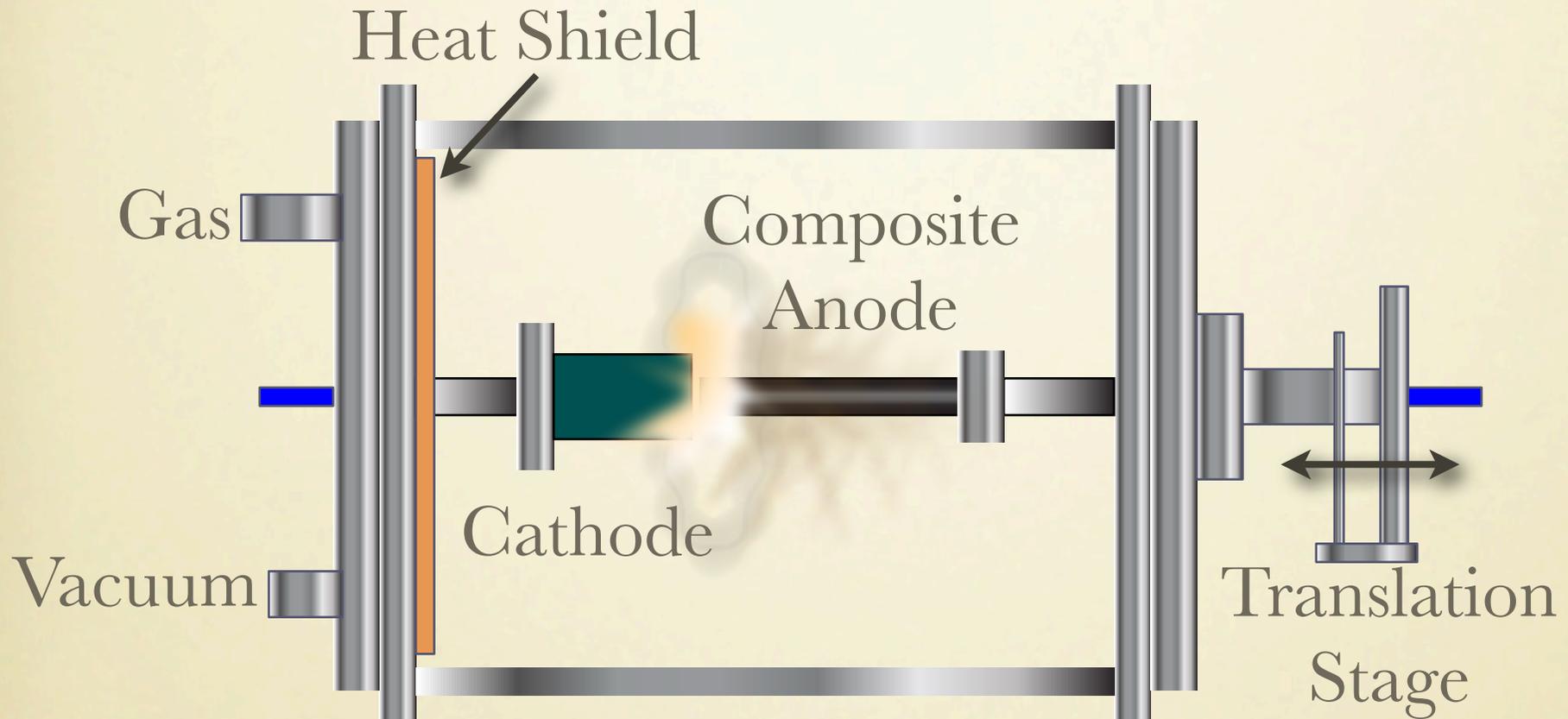
- High aspect ratio fullerenes (nanotubes) synthesized by two primary methods
 - Sublimation + condensation of graphite
 - Decomposition of carbon-containing compounds



MWNT

- T.W. Ebbesen and P.W. Ajayan, “Large scale synthesis of carbon nanotubes,” *Nature* **358**, 220 (1992)
- M. Cadek *et al.*, “Optimization of the arc-discharge production of multi-wall carbon nanotubes,” *Carbon* **40**, 923 (2002)

Arc-Discharge Method



SWNT

- C. Journet, *et al.*, “Large-scale production of single wall carbon nanotubes by the electric-arc technique,” *Nature* **388**, 756 (1997)
- Z. Shi *et al.*, “Mass production of single wall carbon nanotubes by arc-discharge method,” *Carbon* **37**, 1449 (1999)
- M. Takizawa *et al.*, “Change of tube diameter distribution...ratio of Ni and Y catalysts,” *Chem. Phys. Lett.*, **326**, 351 (2000)

SWNT

- T. Guo *et al.*, “Catalytic growth of single-walled nanotubes by laser vaporization,” *Chem. Phys. Lett.* **243**, 49 (1995)
- M. Yudasaka *et al.*, “Single-wall carbon nanotube formation by laser ablation using double targets of carbon and metal,” *Chem. Phys. Lett.* **278**, 102 (1997)
- W.K. Maser *et al.*, “Production of carbon nanotubes: the light approach,” *Carbon* **40**, 1685 (2002)
[focused solar radiation]

LASER ABLATION

- Choose wavelength for minimum absorption depth, maximum energy deposition
- Short pulse duration maximizes peak power, minimizes thermal conduction to surrounding matter
- High pulse repetition rate minimizes heat loss between pulses

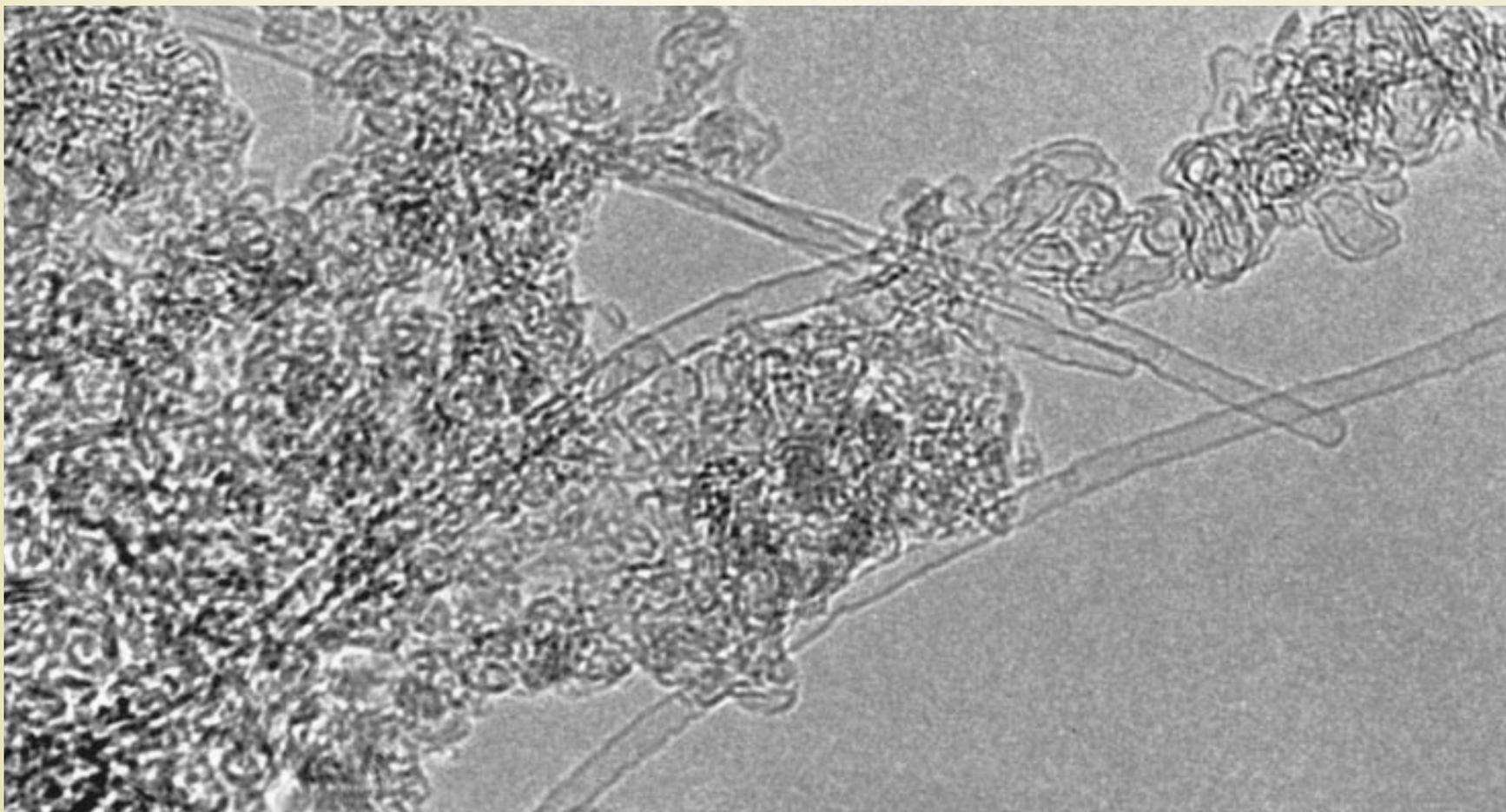
Formation of single-wall carbon nanotubes by laser ablation of fullerenes at low temperature

Y. Zhang^{a)}

Fundamental Research Laboratories, NEC Corporation, 34 Miyukigaoka, Tsukuba, Ibaraki 305-8501, Japan

S. Iijima

*Fundamental Research Laboratories, NEC Corporation, 34 Miyukigaoka, Tsukuba, Ibaraki 305-8501
and Department of Physics, JST International Research Project on Nanotubulites, Meijo University,
Nagoya 468-8502, Japan*





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26 November 1999

**CHEMICAL
PHYSICS
LETTERS**

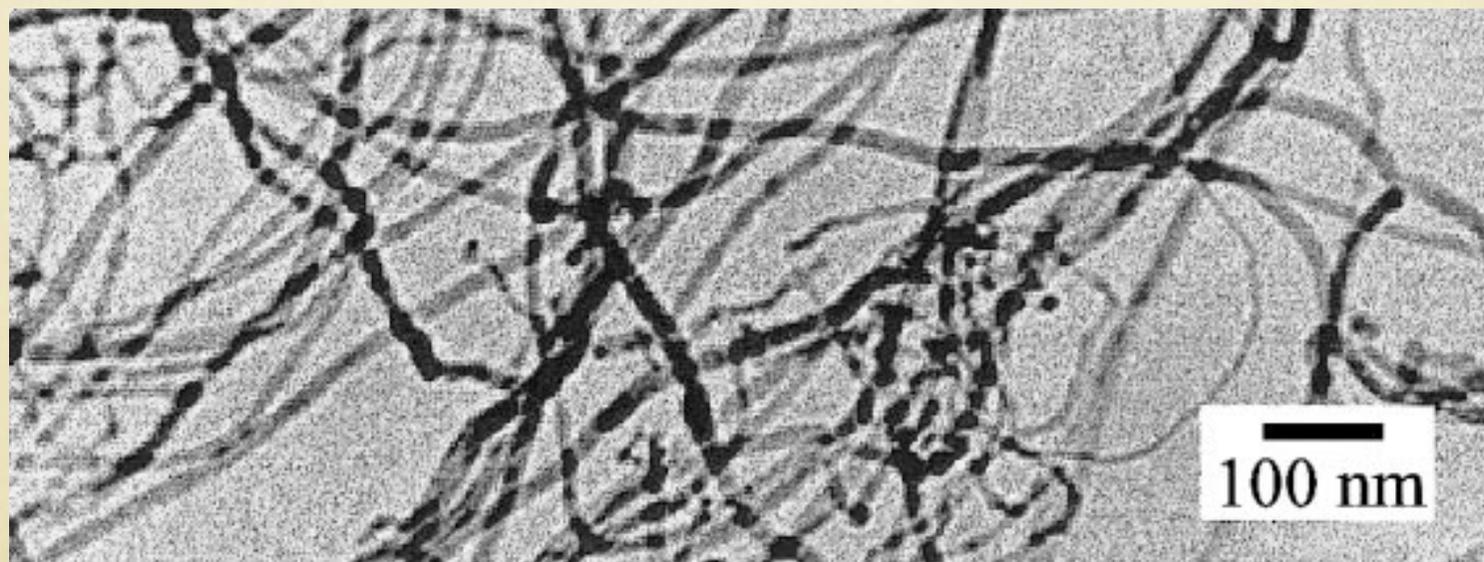
Chemical Physics Letters 314 (1999) 16–20

www.elsevier.nl/locate/cplett

Si nanowires synthesized by laser ablation of mixed SiC and SiO₂ powders

Y.H. Tang, Y.F. Zhang, H.Y. Peng, N. Wang, C.S. Lee, S.T. Lee *

*Center of Super-Diamond and Advanced Films (COSDAF) and Department of Physics and Materials Science,
City University of Hong Kong, Hong Kong, China*



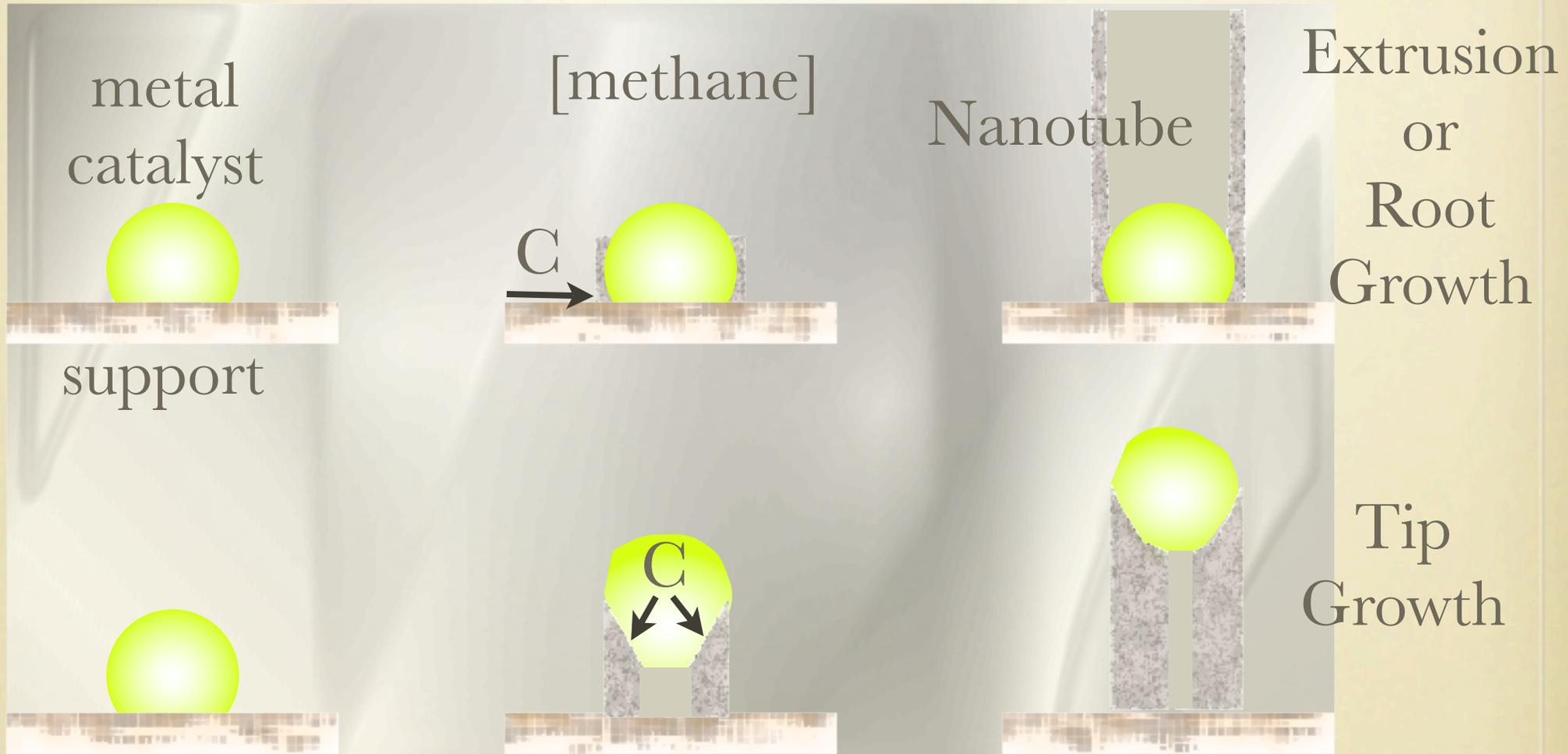
DECOMPOSITION OF CARBON COMPOUNDS

- Pyrolysis of gases: chemical vapor deposition (CVD)
- Pyrolysis of solids (polymers)
- Hydrothermal synthesis from aqueous solutions [J.A. Libera and Y. Gogotski, *Carbon* **39**, 1307 (2001)]
- Organic solutions (supercritical toluene) [D.C. Lee *et al.*, *J. Am. Chem. Soc.* **126**, 4951 (2004)]

CVD

- Heat catalyst material 500-1000°C in tube furnace with flowing hydrocarbon gas (methane)
- Catalyst = Fe, Ni or Co (all have high solubility for C [see phase diagram], supported on porous alumina)
- Dissociation of hydrocarbon molecules by transition metal, dissolution of C by metal, supersaturation
- Precipitation of C from particle leads to tubular carbon solids with sp^2 bonding

CVD



S. B. Sinnot *et al.*, *Chem.Phys.Lett.* **315**, 25-30 (1999)

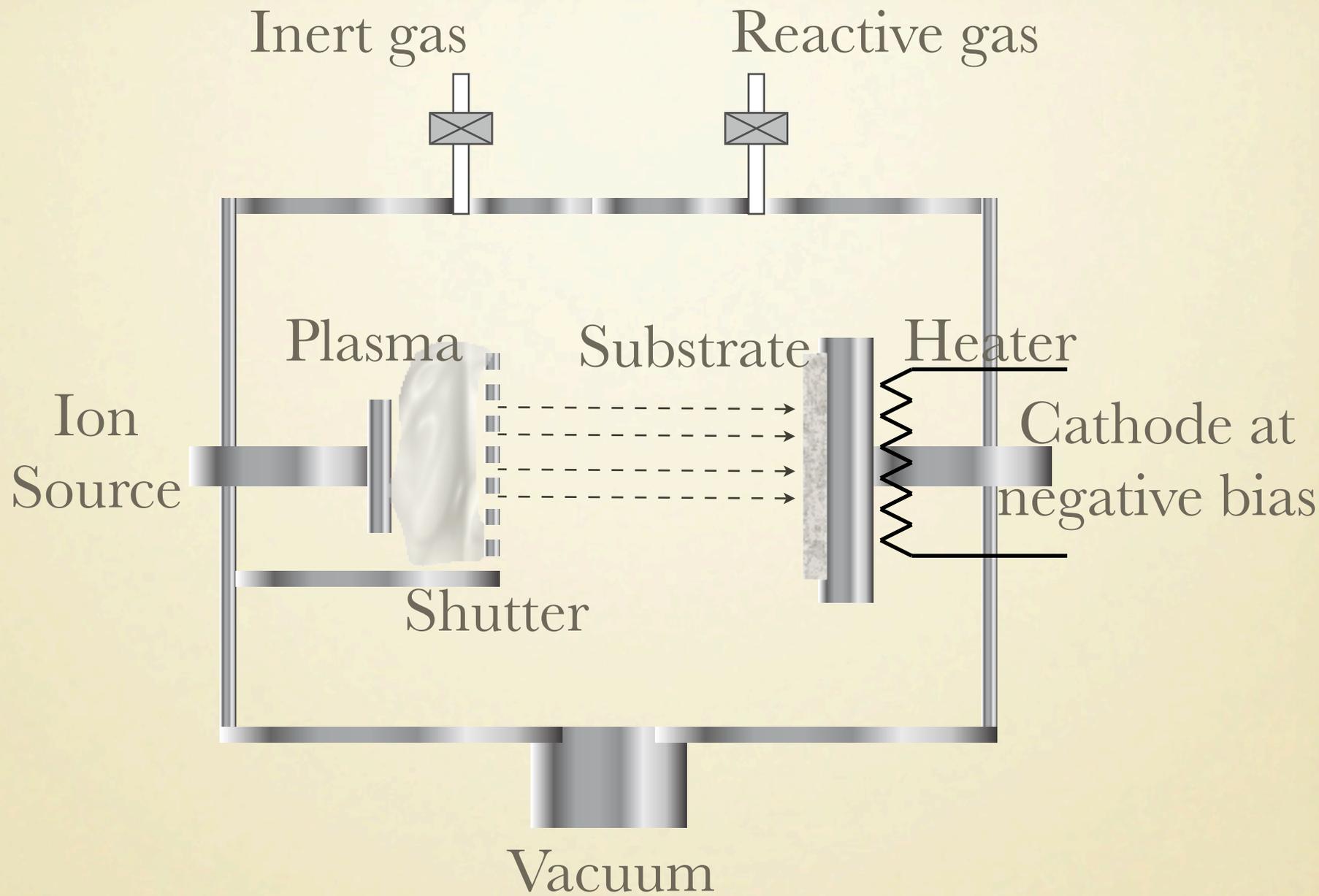
CVD

- A. Cassell *et al.*, “Directed growth of free-standing single-walled carbon nanotubes,” *J. Am. Chem. Soc.* **121** 7975 (1999)
- Lithographic patterning of Si substrate to form pillars
- Contact printing transfers catalyst to tops of pillars
- Nanotubes nucleate on pillar tops, grow directionally

NANO FILMS

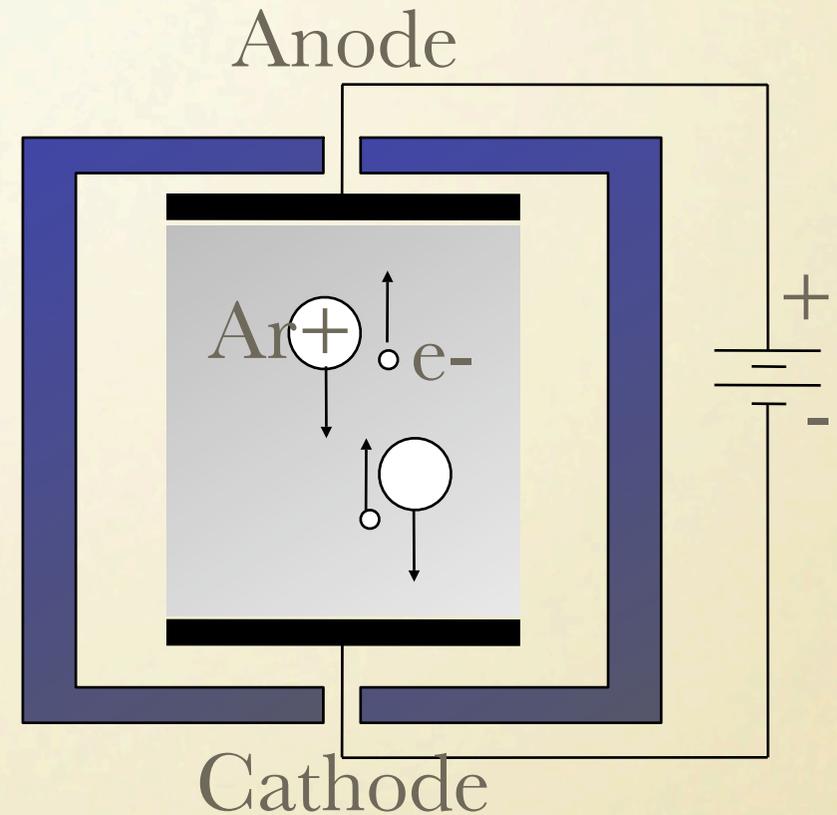
SPUTTERING

- Gas ions collide with target, sputter material from surface, deposit onto substrate
- Gas can be inert (Ar) or reactive (O_2 , N_2)
- Magnetron added beneath target; magnetic field traps electrons in electron tunnel, increasing erosion by increasing gas ion collisions



PLANAR DIODE SOURCE

- High voltage supply ionizes small amount of gas between electrodes
- DC discharge develops, causing sputtering from cathode
- Cathode is water-cooled disk 5-10 cm diameter
- Slow process



TRIODE SOURCE

- Heated filament added to a diode source: provides electrons to sustain the glow discharge, independent of target
- Discharge operates at lower gas pressures (0.5—1 mtorr), and lower target voltage
- Increased ionization efficiency, high deposition rates

MAGNETRON SOURCE

- Magnetic field of 50—500 gauss parallel to target surface
- In combination with electric field causes electrons to drift in a closed circuit or “magnetron tunnel” in front of target
- Electron confinement increases efficiency, resulting in lower gas pressure

MAGNETRON PARAMETERS

- Cathode current density = $20 \text{ mA} / \text{cm}^2$
- Voltage 250 — 800 V
- Target to substrate distance $\approx 10 \text{ cm}$
- Deposition rate ≈ 100 — $2000 \text{ \AA}/\text{min}$
- Current density at cathode is peaked where magnetic field lines are tangent to surface of cathode, causing non-uniform erosion

ION BEAM SOURCE

- Multi-aperture Kaufman ion sources commercially available (Harold Kaufman, NASA-Lewis, 1960's)
- Ar⁺ ion beam up to 10 cm diameter
- 0.5-1.0 A/cm²
- Beam energy 500-2000 eV
- Low background pressure (0.1 mtorr)

ION BEAM SOURCES

- Substrate isolated from ion generation
- Minimal interaction between processes at target and processes at substrate
- Control of ion impact angle and spot size
- Independent control of ion energy and current density

METALLIC FILMS

- **Sputtering** of metals in Ar^+ gas results in easy deposition of conducting films
- Adhesion is superior to evaporation methods: energetic particles from target clean substrate and promote local rearrangements on surface
- Multicomponent targets do not always produce alloy films of same composition: different sputter yields of component species; correction is to use multiple targets (“*co-sputtering*”)

REACTIVE ION SPUTTERING

| TARGET | GAS | FILM |
|--------|----------------|--|
| Si | O ₂ | SiO ₂ |
| Si | N ₂ | SiN ₂ |
| Ti | N ₂ | TiN ₂ |
| In/Sn | O ₂ | In ₂ O ₃ /SnO ₂ |

MICROSTRUCTURES: SPUTTERED FILMS

- “Zone” Model widely accepted
- J.A. Thornton, *J. Vac. Sci. Tech.* **12**, 830 (1975)

ZONE 1

- Zone 1
- $T/T_m < 0.3$
- Tapered columnar grains with intergranular voids

ZONE 2

- Zone 2
- $0.3 < T/T_m < 0.5$
- Columnar, platelet, or whisker grains separated by dense intercrystalline boundaries

ZONE 3

- Zone 3
- $T/T_m > 0.5$
- Equiaxed grains and epitaxial growth on surface

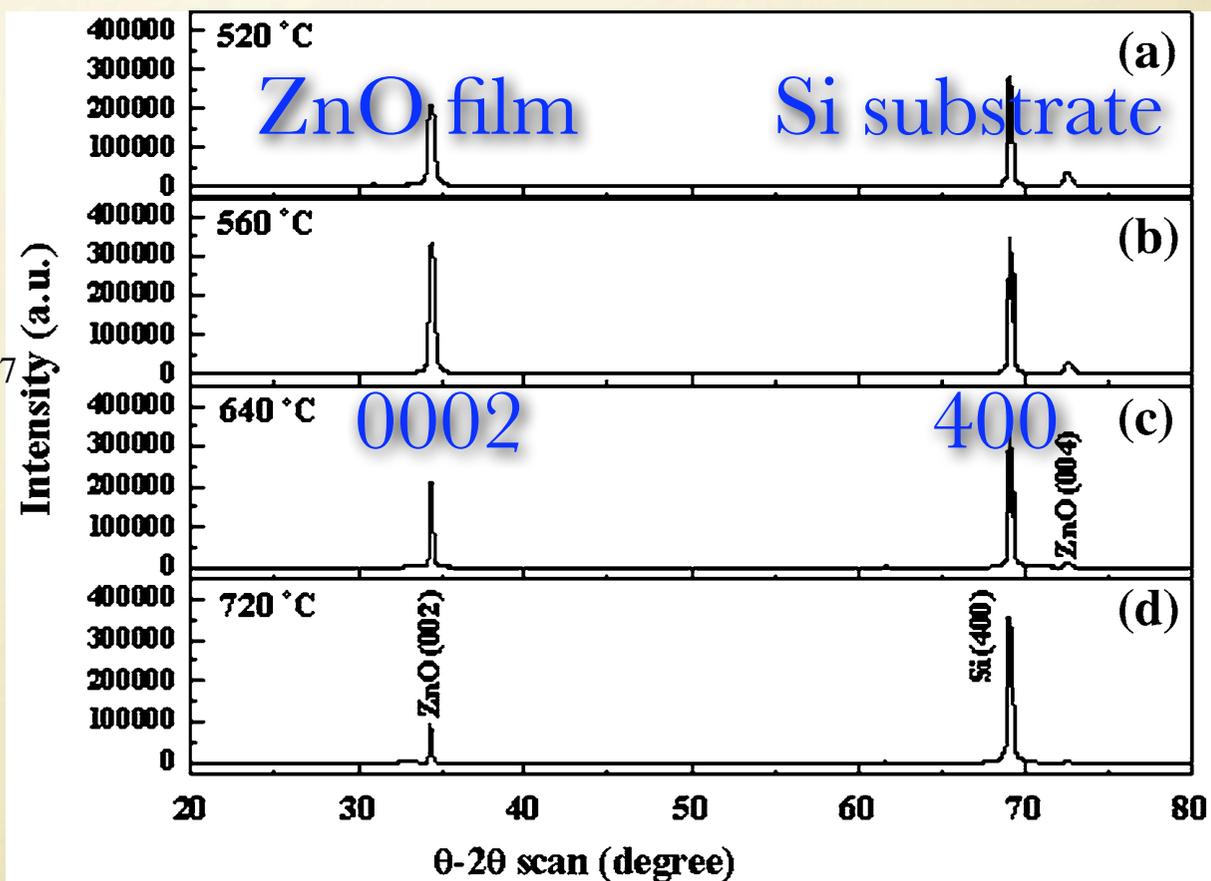
ZONE T

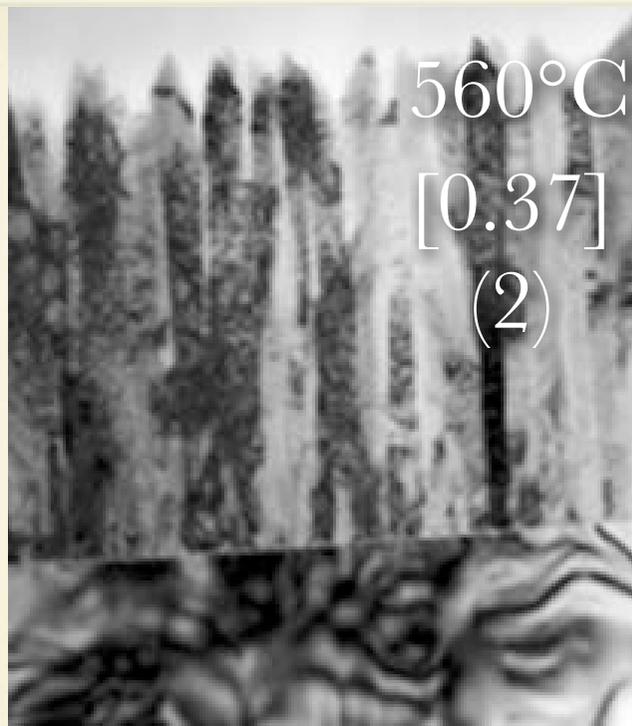
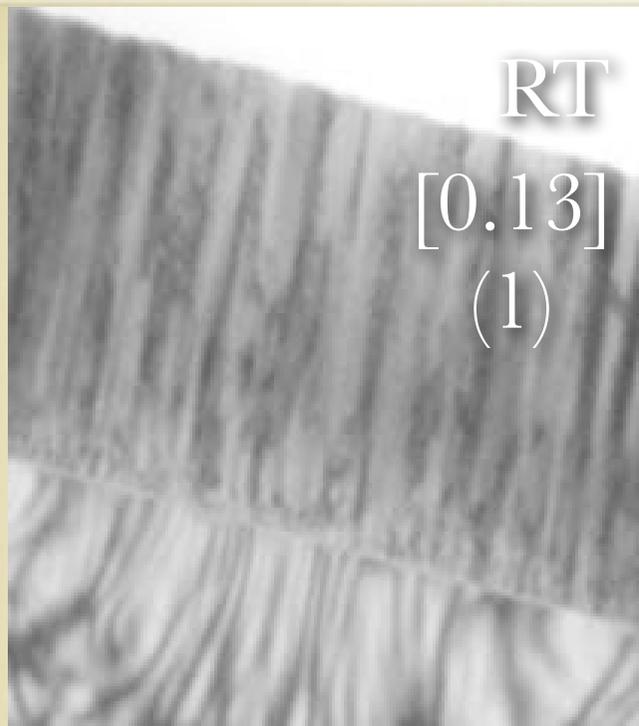
- Zone T
- “Transition” zone, resulting from bombardment-induced surface mobility
- Films that would be expected in Zone 1 can be grown with high density and smooth surface by biasing the substrate (200 V) to increase ion flux
- Bombardment causes compressive stresses in films

Temperature dependence of ZnO thin films grown on Si substrate

Y. Y. Kim · C. H. Ahn · S. W. Kang · B. H. Kong · S. K. Mohanta ·
H. K. Cho · J. Y. Lee · H. S. Kim

Received: 14 May 2007 / Accepted: 30 August 2007
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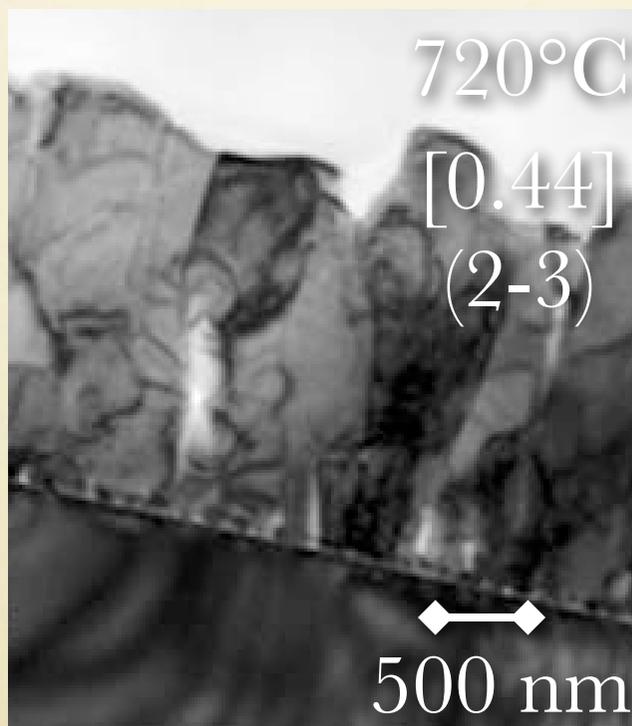




Key: $[T/T_s]$
(Zone)

ZnO

$$T_{sublimation} = 1975^\circ\text{C}$$
$$= 2248 \text{ K}$$



- 1) $T/T_m < 0.3$
- 2) $0.3 < T/T_m < 0.5$
- 3) $T/T_m > 0.5$

MODIFICATIONS

Gas Pulsing

- Periodic pulsing of reactive gas during reactive sputtering process
- Forms alternating layers of metal and dielectric
- Suppresses columnar growth, results in smooth surface finish
- Also stabilizes metallic mode: periodically switching off reactive gas inhibits nucleation of compounds; only metallic constituent nucleates

MODIFICATIONS

Low frequency sputtering

- In the 60 — 100 kHz range, reactive magnetron sputtering is facilitated
- Deposition rate increases up to 80%
- Ions are accelerated by full voltage modulation rather than just self-bias voltage

TECHNICAL CONSIDERATIONS

Targets

- Fabricated by mechanical, sintering, and casting methods, sometimes at very high cost...
- Target utilization can be increased by flattening the magnetic field lines parallel to the target surface

TECHNICAL CONSIDERATIONS

Film Uniformity

- Deposition rate profile depends upon
 - geometry and size of the source,
 - operating pressure
 - target-to-substrate distance

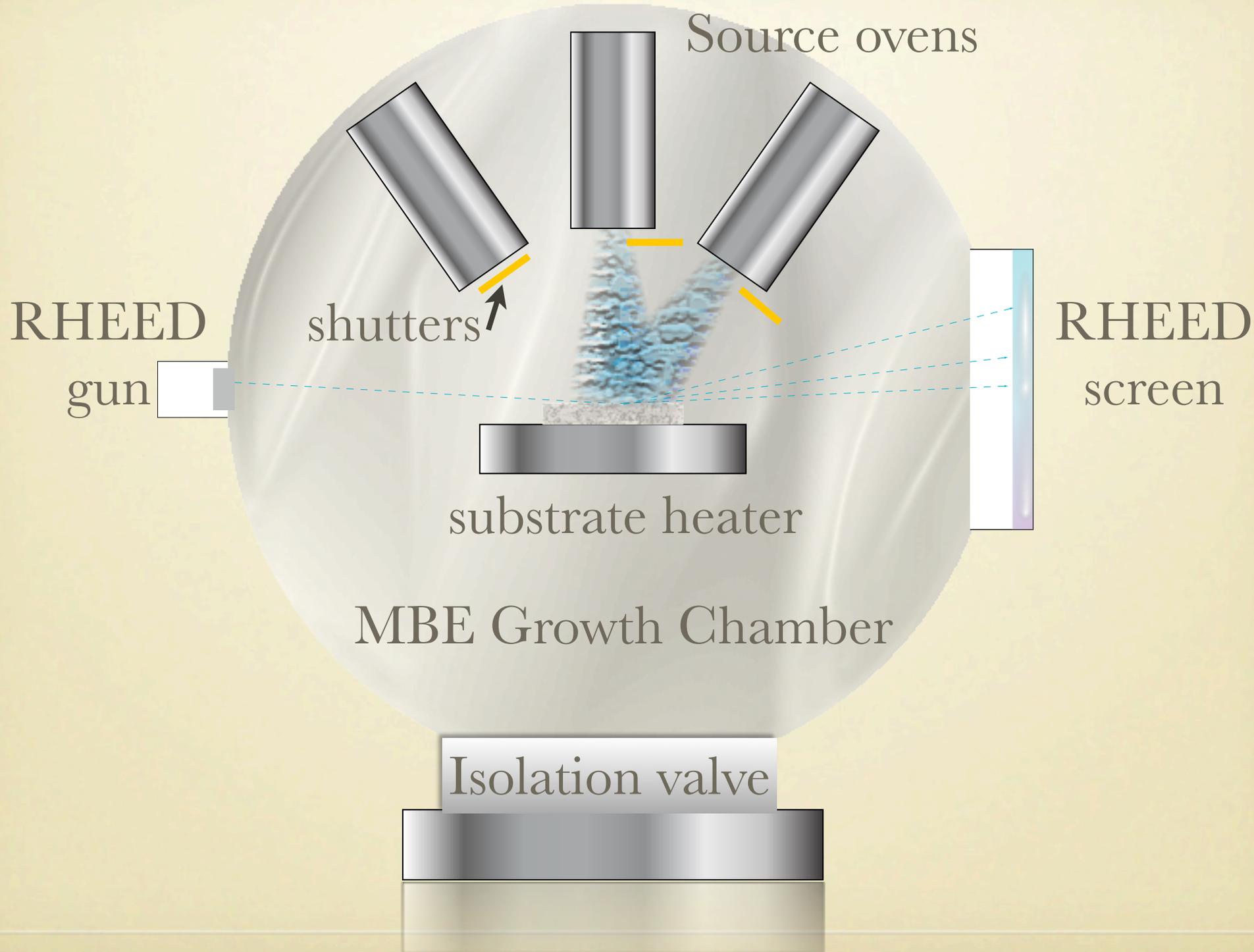
TECHNICAL CONSIDERATIONS

Substrate Preparation

- Glow discharge cleaning favors adhesion
- Vacuum interlocks prevents contamination

MOLECULAR BEAM EPITAXY

- A. Cho and J.R. Arthur, “Molecular Beam Epitaxy,”
Prog. Solid State Chem. **10**, 157 (1975)
- Epitaxial film growth
- Ultrahigh vacuum conditions
- Real time analysis of surface and environment





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Journal of Crystal Growth 289 (2006) 381–386

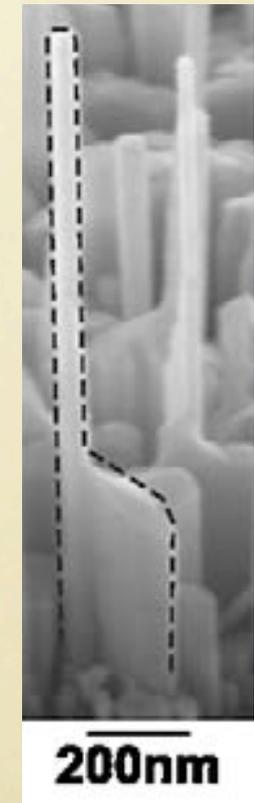
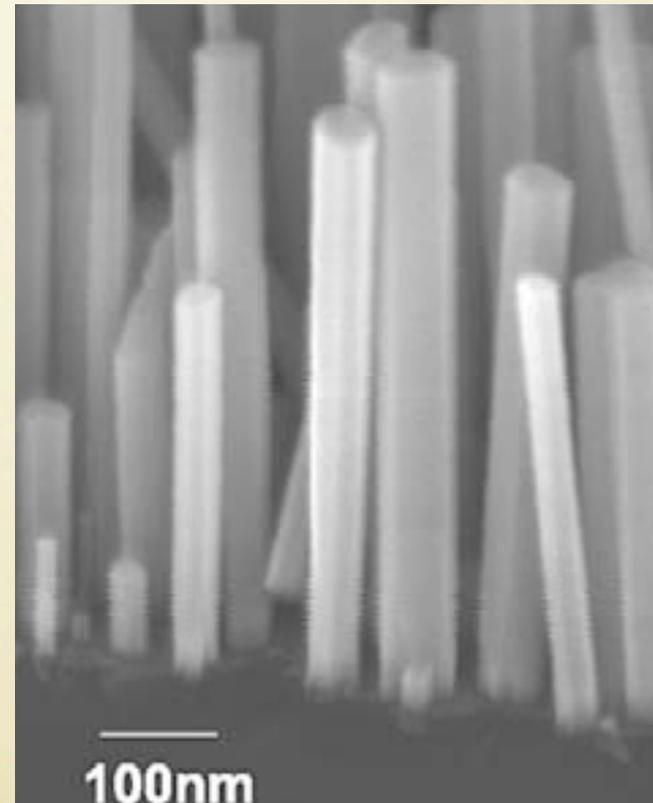
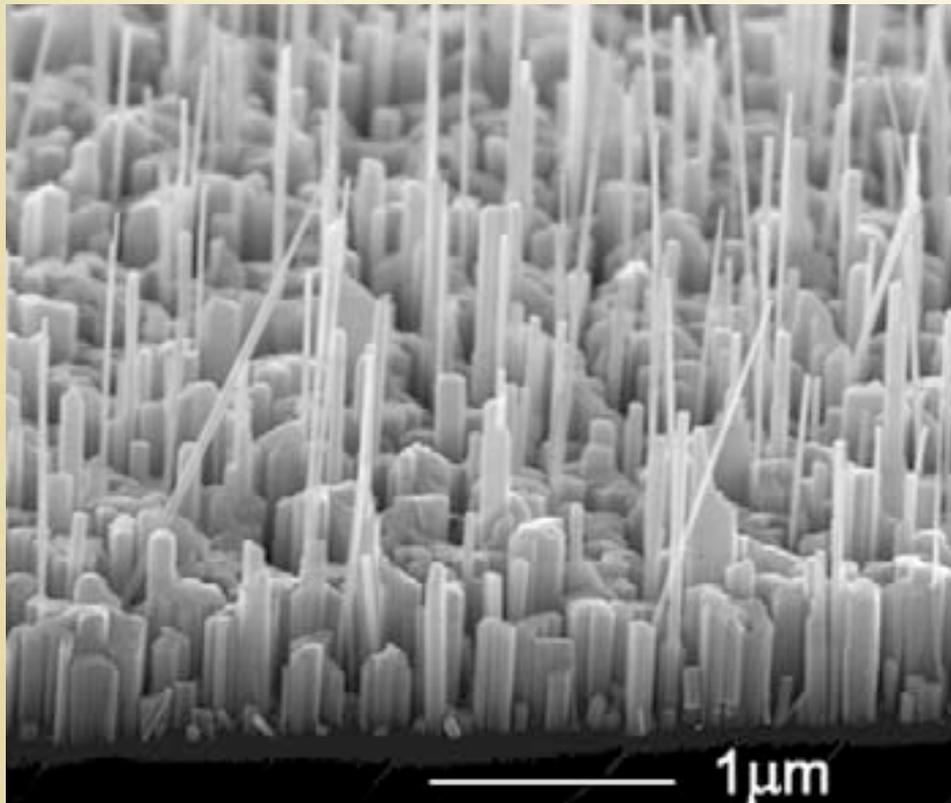
JOURNAL OF **CRYSTAL
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GaN-nanowhiskers: MBE-growth conditions and optical properties

R. Meijers*, T. Richter, R. Calarco, T. Stoica, H.-P. Bochem, M. Marso, H. Lüth

*Institute of Thin Films and Interfaces (ISG1) and cni-Center of Nanoelectronic Systems for Information Technology,
Research Centre Jülich, 52425 Jülich, Germany*



SUMMARY

- Solidification from liquid phase: control of porosity, shrinkage, constitutional supercooling, solute partitioning (can be used to advantage)
- Deposition from vapor phase: CVD, Sputtering, PLD for production, MBE for scientific evaluation

END

LECTURE 08